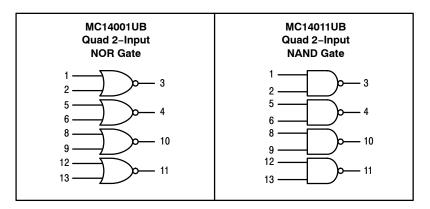
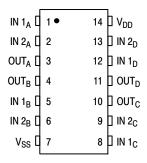
LOGIC DIAGRAMS



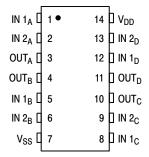
 V_{DD} = PIN 14 V_{SS} = PIN 7 FOR ALL DEVICES

PIN ASSIGNMENTS

MC14001UB Quad 2-Input NOR Gate



MC14011UB Quad 2-Input NAND Gate



ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

				- 55°C		25°C		125°C			
Characterist	ic	Symbol	V _{DD} Vdc	Min	Max	Min	Typ (Note 2)	Max	Min	Max	Unit
Output Voltage V _{in} = V _{DD} or 0	"0" Level	V _{OL}	5.0 10 15	- - -	0.05 0.05 0.05	- - -	0 0 0	0.05 0.05 0.05	- - -	0.05 0.05 0.05	Vdc
$V_{in} = 0$ or V_{DD}	"1" Level	V _{OH}	5.0 10 15	4.95 9.95 14.95	- - -	4.95 9.95 14.95	5.0 10 15	- - -	4.95 9.95 14.95	- - -	Vdc
Input Voltage $(V_O = 4.5 \text{ Vdc})$ $(V_O = 9.0 \text{ Vdc})$ $(V_O = 13.5 \text{ Vdc})$	"0" Level	V _{IL}	5.0 10 15	- - -	1.0 2.0 2.5	- - -	2.25 4.50 6.75	1.0 2.0 2.5	- - -	1.0 2.0 2.5	Vdc
$(V_O = 0.5 \text{ Vdc})$ $(V_O = 1.0 \text{ Vdc})$ $(V_O = 1.5 \text{ Vdc})$	"1" Level	V _{IH}	5.0 10 15	4.0 8.0 12.5	- - -	4.0 8.0 12.5	2.75 5.50 8.25	- - -	4.0 8.0 12.5	- - -	Vdc
Output Drive Current $ \begin{aligned} &(V_{OH}=2.5 \text{ Vdc})\\ &(V_{OH}=4.6 \text{ Vdc})\\ &(V_{OH}=9.5 \text{ Vdc})\\ &(V_{OH}=13.5 \text{ Vdc}) \end{aligned} $	Source	I _{OH}	5.0 5.0 10 15	- 1.0 - 0.25 - 0.62 - 1.8	- - -	- 0.75 - 0.2 - 0.4 - 1.5	- 1.7 - 0.36 - 0.9 - 3.5	- - - -	- 0.55 - 0.14 - 0.15 - 1.0	- - -	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	Sink	I _{OL}	5.0 10 15	0.64 1.6 4.2	- - -	0.51 1.1 3.4	0.88 2.25 8.8	- - -	0.36 0.7 2.4	- - -	mAdc
Input Current		I _{in}	15	-	± 0.1	-	±0.00001	± 0.1	-	± 1.0	μAdc
Input Capacitance (V _{in} = 0)		C _{in}	-	-	-	-	5.0	7.5	-	-	pF
Quiescent Current (Per Package)		I _{DD}	5.0 10 15	- - -	0.25 0.5 1.0	- - -	0.0005 0.0010 0.0015	0.25 0.5 1.0	- - -	7.5 15 30	μAdc
Total Supply Current (N (Dynamic plus Quies Per Gate C _L = 50 p	scent,	Ι _Τ	5.0 10 15			$I_{T} = (0.0)$	3 μA/kHz) f - 6 μA/kHz) f - 8 μA/kHz) f -	- I _{DD} /N	•		μAdc

Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
 The formulas given are for the typical characteristics only at 25°C.
 To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

where: I_T is in μH (per package), C_L in pF, $V = (V_{DD} - V_{SS})$ in volts, f in kHz is input frequency, and k = 0.001 x the number of exercised gates per package.

SWITCHING CHARACTERISTICS (Note 5) ($C_L = 50 \text{ pF}, T_A = 25^{\circ}C$)

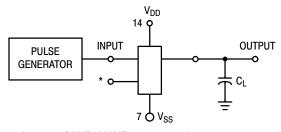
Characteristic	Symbol	V _{DD} Vdc	Min	Typ (Note 6)	Max	Unit
Output Rise Time	t _{TLH}					ns
$t_{TLH} = (3.0 \text{ ns/pF}) C_L + 30 \text{ ns}$		5.0	_	180	360	
$t_{TLH} = (1.5 \text{ ns/pF}) C_L + 15 \text{ ns}$		10	_	90	180	
$t_{TLH} = (1.1 \text{ ns/pF}) C_L + 10 \text{ ns}$		15	_	65	130	
Output Fall Time	t _{THL}					ns
$t_{THL} = (1.5 \text{ ns/pF}) C_L + 25 \text{ ns}$		5.0	_	100	200	
t _{THL} = (0.75 ns/pF) C _L + 12.5 ns		10	_	50	100	
$t_{THL} = (0.55 \text{ ns/pF}) C_L + 9.5 \text{ ns}$		15	_	40	80	
Propagation Delay Time	t _{PLH} , t _{PHL}					ns
t_{PLH} , $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 30 \text{ ns}$		5.0	_	90	180	
t_{PLH} , $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 22 \text{ ns}$		10	_	50	100	
t_{PLH} , $t_{PHL} = (0.50 \text{ ns/pF}) C_L + 15 \text{ ns}$		15	_	40	80	

^{5.} The formulas given are for the typical characteristics only at 25°C.6. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

ORDERING INFORMATION

Device	Package	Shipping [†]		
MC14001UBCPG	PDIP-14 (Pb-Free)	25 Units / Rail		
MC14001UBDG	SOIC-14	55 H-7- / D-7		
NLV14001UBDG*	(Pb-Free)	55 Units / Rail		
MC14001UBDR2G	SOIC-14			
NLV14001UBDR2G*	(Pb-Free)	2500 / Tape & Reel		
	•			
MC14011UBCPG	PDIP-14	os Heile (Beil		
NLV14011UBCPG*	(Pb-Free)	25 Units / Rail		
MC14011UBDG	SOIC-14	55 Units / Rail		
NLV14011UBDG*	(Pb-Free)			
MC14011UBDR2G	SOIC-14	0700 /T		
NLV14011UBDR2G*	(Pb-Free)	2500 / Tape & Reel		

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



^{*}All unused inputs of AND, NAND gates must be connected to V_{DD}.
All unused inputs of OR, NOR gates must be connected to V_{SS}.

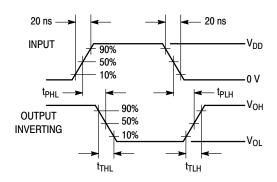
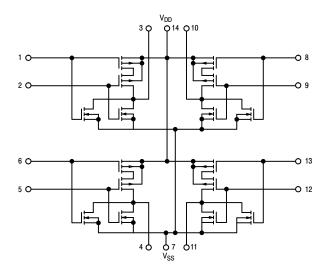


Figure 1. Switching Time Test Circuit and Waveforms

^{*}NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

MC14001UB CIRCUIT SCHEMATIC



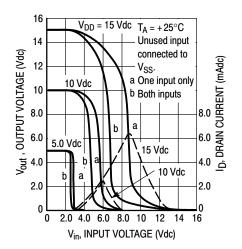


Figure 2. Typical Voltage and Current Transfer Characteristics

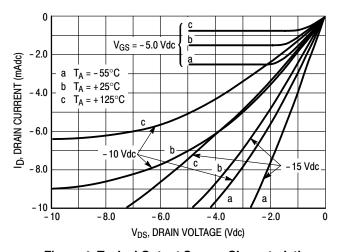
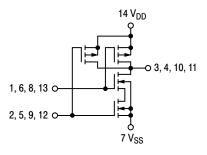


Figure 4. Typical Output Source Characteristics

MC14011UB CIRCUIT SCHEMATIC (1/4 of Device Shown)



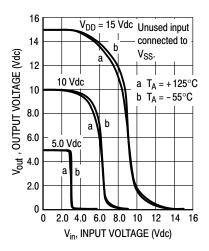


Figure 3. Typical Voltage Transfer Characteristics versus Temperature

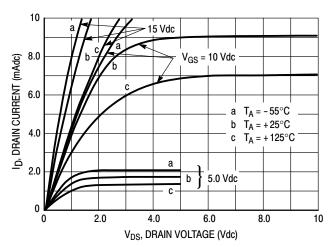
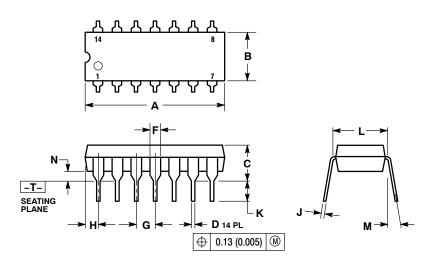


Figure 5. Typical Output Sink Characteristics

PACKAGE DIMENSIONS

PDIP-14 CASE 646-06 ISSUE P

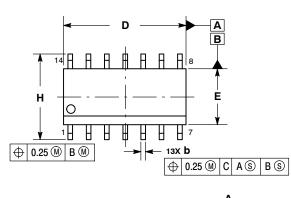


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL.

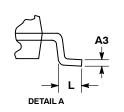
	INC	HES	MILLIMETERS			
DIM	MIN	MAX	MIN	MAX		
Α	0.715	0.770	18.16	19.56		
В	0.240	0.260	6.10	6.60		
С	0.145	0.185	3.69	4.69		
D	0.015	0.021	0.38	0.53		
F	0.040	0.070	1.02	1.78		
G	0.100 BSC		2.54 BSC			
Н	0.052	0.095	1.32	2.41		
J	0.008	0.015	0.20	0.38		
K	0.115	0.135	2.92	3.43		
L	0.290	0.310	7.37	7.87		
М		10 °		10 °		
N	0.015	0.039	0.38	1.01		

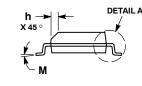
PACKAGE DIMENSIONS

SOIC-14 NB CASE 751A-03 **ISSUE K**



е



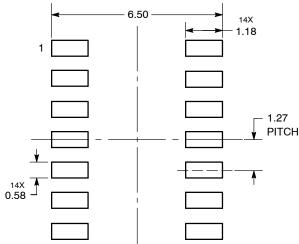


- 1. DIMENSIONING AND TOLERANCING PER
- DIMENSIONING AND TOLEHANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
 4. DIMENSIONS D AND E DO NOT INCLUDE
- MOLD PROTRUSIONS
- 5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	1.35	1.75	0.054	0.068	
A 1	0.10	0.25	0.004	0.010	
АЗ	0.19	0.25	0.008	0.010	
b	0.35	0.49	0.014	0.019	
D	8.55	8.75	0.337	0.344	
Е	3.80	4.00	0.150	0.157	
е	1.27 BSC		0.050	BSC	
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.019	
L	0.40	1.25	0.016	0.049	
М	0°	7°	0 °	7°	

SOLDERING FOOTPRINT* 6.50

C SEATING PLANE



DIMENSIONS: MILLIMETERS

ON Semiconductor and un are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of SCILLC's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent—Marking.pdf. SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA

Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada **Fax**: 303–675–2176 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910 Japan Customer Focus Center

Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

MC14001UB/D

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.